Chemical Mechanical Polishing CMP

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Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

Safety

Process Restrictions

Material Restrictions
- 3", 4", and 6: whole wafers only
- Wafers must not be excessively thin or thick
- No GaAs

Parameter Restrictions

Scheduling / Sign-up Restrictions
None

Requirements (Do Every Time)
- Check wafer extension prior to polishing
- Enter all time and supplies used in log and CAC
- Purge slurry lines and remove carrier head from tool
- Place tool in went idle state when done
- Clean tool and work area when done

Prohibitions (Never Do)

Common Problems

Problem: Root Cause: Solution:
- Tool hangs during wafer load - Low vacuum - Stop recipe. Go into manual and return polish arm to over table. Wait until house vacuum is over 650 mm Hg.

Other Comments or Cautions